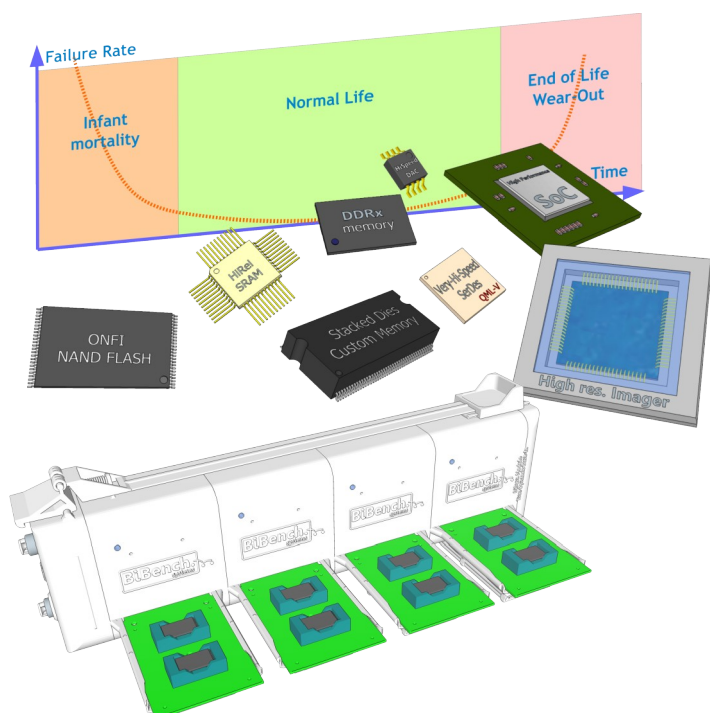


BIBURN : TRUE DYNAMIC BURN-IN / LIFE-TEST SOLUTION

→ Testing high speed / complex
components under
actual operating conditions



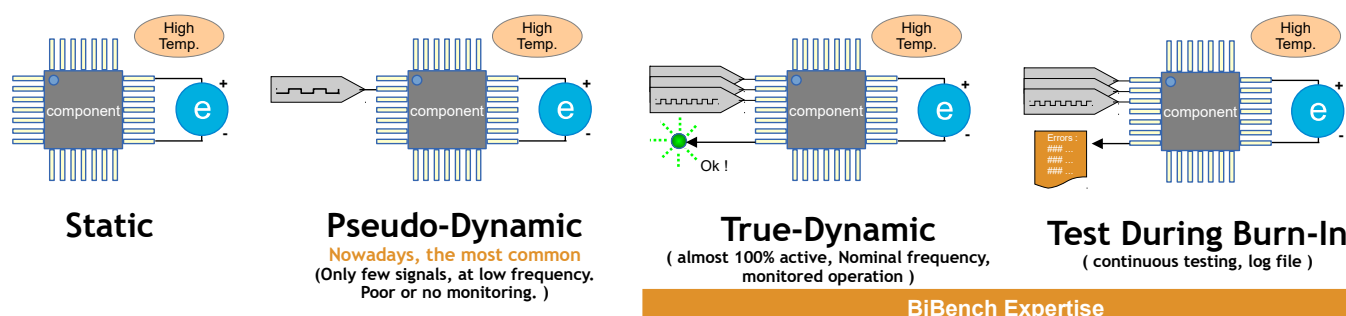
- ✓ System usable at high or low temperature for high-end component functional tests.
- ✓ Nominal operation qualification under stress!
- ✓ True dynamic aging solution for DDRx, High Capacity Nand Flash, High Res Image Sensor, etc. Available now!
- ✓ Designed to be used in your existing oven thanks to the patented « air-cooled » system : no equipment change!
- ✓ Easy to use: "on-desk" comfortable component installation. Easy to handle system with in-oven latch and automatic connection.
- ✓ Reconfigurable, reusable for different component types and different developments.

BiBurn benefits?

This approach originated in the space field for several reasons:

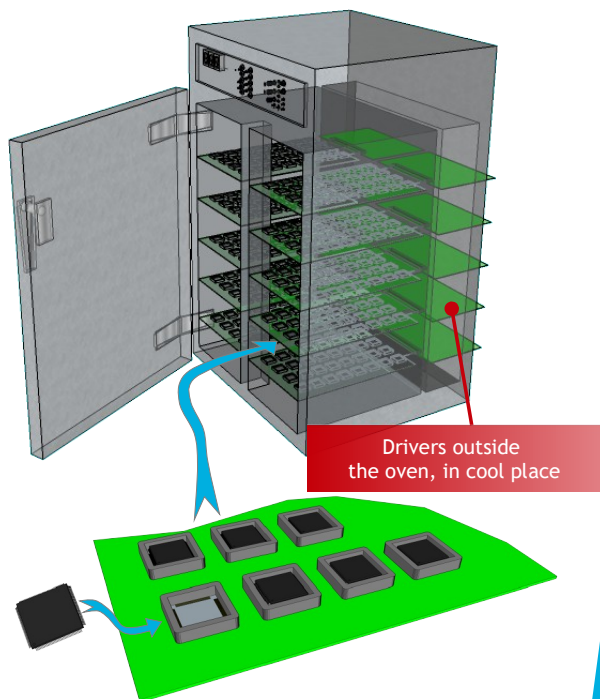
- ✓ Many of existing component tests activate only an extremely limited surface of the die (e.g. DDR-Sdram) and do not stress the sensitive parts of components (e.g. Flashes / floating gate).
- ✓ Some recent components, such as FPGA, SoC, etc ... , may present fault trees whose intricacies follow their own complexity. BiBurn systems helps you address this issue by allowing test under real conditions.
- ✓ Nowadays the life expectancy for a commercial component (smart-phone, computer...) is less than 4 or 5 years against 10 years formerly. Using these components for reliable applications therefore requires deeper tests. Keep cool : our systems are there for that !
- ✓ Highly qualitative tests compared to static burn-in or pseudo-dynamic testing: brings more failure modes with more objective results for better Go/NoGo sorting.
- ✓ Optimized test time:
 - For flawed component, no parametric test required ...
 - Independent test slots: partial batches possible, the stop of a faulty component has no influence on others ...
 - Defective component are instantly detected: replace and restart position with no dead time.
- ✓ Reliable system, recognized in the space field.

Evolution of Burn-in / Life-Test conditions

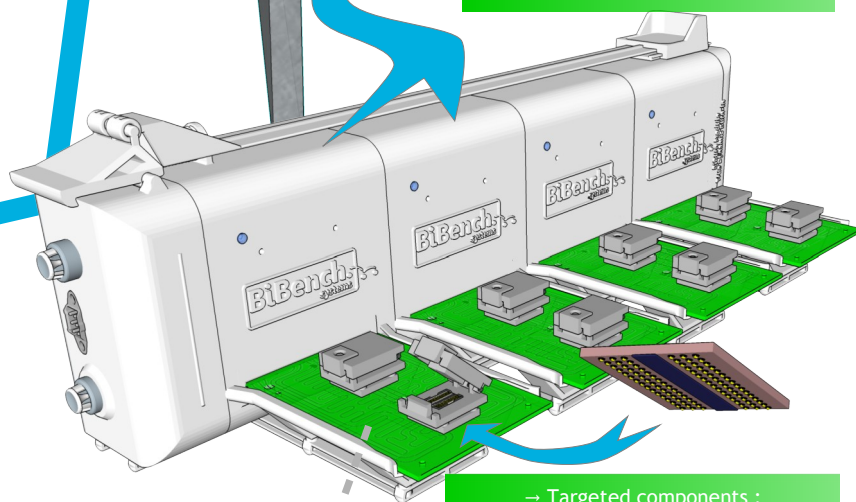
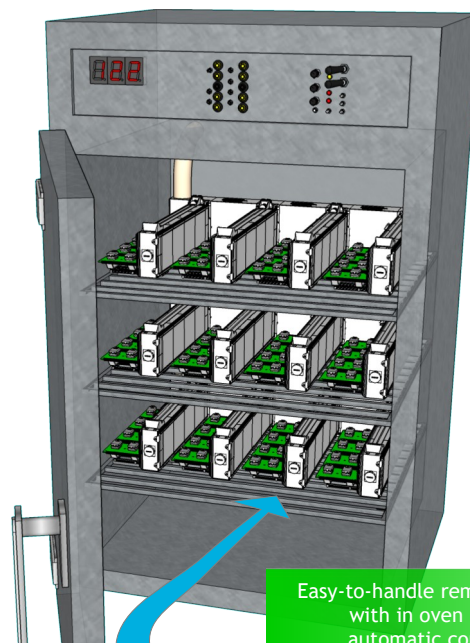


☒ Usual systems :
True Dynamic Not Possible

☒ Bibench Systems :
True Dynamic Possible



- Centralized power supplies far away → poor bandwidth
- Driver too far → no high speed
- Not enough connections/component = parallelization
- No individual temperature monitoring



- In oven, nearby driver protected from thermal stress thanks to an innovative housing (patented)
- One or small count of DUT per Driver
- Close and performing programmable power supplies (high di/dt)
- High I/O count & matched impedance (if necessary)
- Local, accurate temperature & current monitoring
- Versatile, reprogrammable, reusable, reasonable recurring cost, reasonable NRE cost for new project

